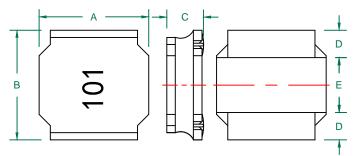
TYS5040101M-10

PHYSICAL DIMENSIONS:

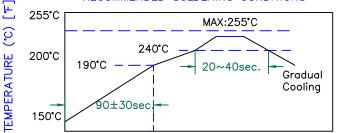
A 5.00 ± 0.20 B 5.00 ± 0.20

4.00 - 0.30

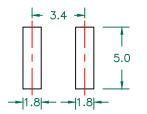
D 1.60 ± 0.30 E 1.80 ± 0.30

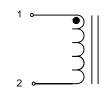


RECOMMENDED SOLDERING CONDITIONS



LAND PATTERNS FOR REFLOW SOLDERING

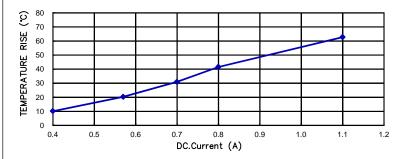




ELECTRICAL SPECIFICATION

	Min	Nom	Max	
INDUCTANCE (uH) L @ 100 KHz/1V ± 20%	80	100	120	
DCR (Ω)		0.560	0.672	

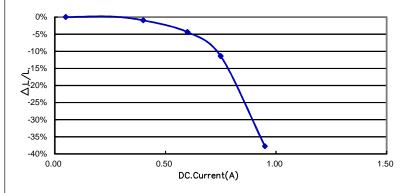
CHARACTERISTICS OF TEMPERATURE RISE





Saturation Current(A)	0.75
SRF (MHz)	4.7
Temperature Rise Current (A)	0.70

CURRENT VS INDUCTANCE DROP IN RATES



NOTES:

- 1.OPERATION TEMPERATURE RANGE: -40°C~+125°C (INCLUDING SELF-HEATING).
- 2.STORAGE TEMPERATURE RANGE (PACKAGING CONDITIONS): -10°C TO +40°C AND RH 70% (MAX.)
- 3.UNLESS OTHERWISE SPECIFIED, THE STANDARD ATMOSPHERIC CONDITIONS FOR MEASUREMENT/TEST AS:
 A. AMBIENT TEMPERATURE: 20±15°C.
 B. RELATIVE HUMIDITY: 65%±20%.
- 4.SATURATION CURRENT IS THE DC CURRENT AT WHICH THE INDUCTANCE DROPS OFF APPROXIMATELY 30% FROM ITS VALUE WITHOUT CURRENT.(AMBIENT TEMPERATURE 25±5°C)

5.TEMPERATURE RISE CURRENT (IRMS):

DC CURRENT THAT CAUSES THE TEMPERATURE RISE (△T ≤40°C) FROM 25°C AMBIENT.

		DIMENSIONS ARE IN mm .			This print is the property of Lain Tech. and is loaned in confidenc subject to return upon request with the understanding that no copies shall be made without th written consent of Laird Tech. A rights to design or invention are reserved.	Laird				
ı					PROJECT/PART NUMBER:	Т	REV	PART T	rPE:	DRAWN BY:
	С	MODIFY "C,D,E"	04/26/16		TYS5040101M-10		С		WER ICTOR	QIU
	В	CHANGE TEMP FROM -25℃~+125℃	12/21/12	QIU	DATE: 05/31/12	SCALE		TS	SHEET:	
	Α	ORIGINAL DRAFT	05/31/12	QIU						
	REV	DESCRIPTION	DATE	INT			_		1	of 1